

Optimizing HIP Applications

Sam Antao LUMI Comprehensive Training Oct 31st, 2024

> AMDA together we advance_

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- Agenda 1. Overview of Kernel Performance Limiters
	- 2. How to optimize memory bound kernels
	- 3. How to optimize compute bound kernels
	- 4. How to optimize latency bound kernels

GPUs are high throughput devices

• Must expose parallelism to properly utilize them

GPU starvation – under-utilization of resources

Full utilization of resources

Optimization strategy depends on performance limiters

Memory bound

 \circ Low arithmetic intensity, memory units saturated

Compute bound

o High arithmetic intensity, compute units saturated

Latency bound

o Memory units not saturated and/or compute units not saturated

Focus of this presentation – what to do for these different types of kernels?

Memory Bandwidth Bound

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Data Movement

- Reducing data movement is still very important for GPU performance
	- Move data, compute as much as possible with that data
- Reuse data when possible temporal reuse and spatial reuse
- Stage data in shared memory (LDS) or registers for faster access
- Lower precision data types move fewer bytes, evaluate their use for your algorithm
- Move more data per work-item to improve streaming efficiency

Data Access Considerations

- Coalesced loads/stores improve achieved bandwidth of transfers
	- L1 cacheline size is 64 bytes in MI200 GPUs, and 128 bytes in MI300 GPUs
	- Use as much as possible of each cacheline read
	- Strided accesses may load more data than needed
- Use vector data types such as float4, float2
	- Compiler generates fewer, wider load instructions
	- Amortize on cost of address/index calculations
	- Improve data streaming efficiency
- Use non-temporal loads for data that will not be reused
- Aligned memory accesses avoid excess data from being fetched

Sometimes compiler generates wider loads/stores for free

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Compute Bound

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Compute Optimizations

- Compute bound kernels perform O(100) operations per byte loaded
	- Large GEMMs are an example of compute bound kernels, but HPC workloads are typically memory bound
- Pre-compute values to look up in kernel
- Use faster math intrinsic functions, e.g., $_\text{cosf}(x)$ instead of cosf(x)
	- More details: https://rocm.docs.amd.com/projects/HIP/en/latest/reference/math_api.html
- Avoid general math functions where possible
	- a $*$ a $*$ a uses two instructions whereas pow(a, 3.0f) uses many
	- Godbolt link:<https://godbolt.org/z/8hz8P4oc9>
- Explore use of packed FP32 operations that process two FP32 values in one instruction
	- For example, using float2 instead of float can result in the use of packed instructions

Compute Optimizations (contd.)

- Where you stage data for your compute matters
	- To make your kernel truly compute-bound, read from registers
	- Moving data from shared memory and/or cache takes O(10) cycles
- For specific matrix multiplication like calculations, special hardware units exist (rocWMMA)
	- AMD Matrix Cores ROCm Blog: <https://rocm.blogs.amd.com/software-tools-optimization/matrix-cores/README.html>

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Unexpected Instructions

```
global void conversions (float *a) {
   float f1 = a[threadIdx.x] * 0.3;
   float f2 = 2.0 * (f1 * 3.0);a[threadIdx.x] = f1 + f2;}
```
 $_\$ global $_\$ void no $_\$ conversions (float * a) { float $f1 = a[threadIdx.x] * 0.3f;$ float f2 = $2.0f * (f1 * 3.0f);$ $a[threadIdx.x] = f1 + f2;$ }


```
s load dwordx2 s[0:1], s[4:5], 0x0
v_lshlrev_b32_e32 v0, 2, v0
s waitcnt lgkmcnt(0)
global load dword v1, v0, s[0:1]s waitcnt vmcnt(0)
v_mul_f32_e32 v1, 0x3e99999a, v1
v_mul_f32_e32 v2, 0x40400000, v1
v_fmac_f32_e32 v1, 2.0, v2
global store dword v0, v1, s[0:1]s_endpgm
```
Fewer instructions, FP32 ops

Latency bound

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Main Ideas for Optimizing Latency Bound Kernels

- Increase parallelism to utilize all GPU resources
- Reduce number of synchronization barriers
- Reduce thread divergence
- Avoid register spilling to slower "scratch" memory

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[Public]

Motivation for Launching Many Wavefronts

- The GPU has a lot of resources
- Wavefronts can stall for various reasons:
	- Waiting for data to load
	- Waiting at a synchronization barrier
- GPU is good at switching to wavefronts with instructions ready to be executed
- **→ Good to launch a lot of wavefronts and hide latencies of stalls**

What is Occupancy?

- # Resident wavefronts / Maximum #wavefronts the GPU can have in-flight
- Hardware Perspective (let's consider a MI250x GPU):
	- There are 110 Compute Units (CU)
	- Up to 32 wavefronts can be scheduled to each $CU = max 3520$ wavefronts
- Developers' Perspective:
	- Am I launching enough units of work to use all CUs?
	- Am I launching more wavefronts than the number of CUs to hide latencies?
- Higher occupancy can help improve performance, but not always

Occupancy by Example (daxpy)

 $Z = aX + Y$ where Z, X and Y are 1D arrays of length $N = 1,000,000$ elements

We know that

- a workgroup can have 64 to 1024 work-items $= 1$ to 16 wavefronts
- all wavefronts of a workgroup will be scheduled to the same CU

We can launch the daxpy kernel in many ways:

1 workgroup with 64 work-items

Only 1 wave on 1 $CU = No$ latency hiding

1 workgroup with 256 work-items Only 4 waves on 1 CU = All other CUs idle

N/1024 workgroups, each workgroup has 16 waves \sim 1000 workgroups = \sim 16000 waves = good occupancy

But that's not the whole picture..

Memory Resources that affect Occupancy

Compute Units have finite resources that are shared between work items

- Local Data Share (LDS)
- Vector General Purpose Registers (VGPRs)
- Scalar General Purpose Registers (SGPRs)

The GPU can only schedule more work if there are enough resources available

[Public]

How LDS affects Occupancy

- Fast, on-CU, software managed memory to efficiently share data between work-items of a workgroup
- Each CU in a MI200 GPU has 64 KiB of LDS available
- Shared by workgroups on CU

No LDS used, LDS does not limit occupancy

8 KiB of LDS per WG, 8 WGs can fit in CU

48 KiB of LDS per WG, only 1 WG can fit in CU

How Vector Registers affect Occupancy

- In VGPRs, each thread in the wavefront can save its own value
- Each MI200 CU has a limited size vector register file (max 512 VGPRs of size 4 bytes)

This is the column that corresponds to the compiler and profiler report.

[Public]

How Scalar Registers (SGPRs) affect Occupancy

- In SGPRs, one value is shared across all work-items of the wavefront
- Each MI200 CU has a limited size scalar register file (max 102 SGPRs of size 4 bytes per wavefront)

A Note about Register Spilling

- Register allocation is done by the compiler at compilation time
- When the required number of VGPRs is too much (i.e., > 256), the compiler may "spill" registers to slower "scratch" memory
	- Better to avoid spilling in most cases
- By default, the compiler assumes workgroups are going to have 1024 work-items
	- Use launch bounds on smaller workgroups to allow the compiler to use more registers
- The compiler may spill SGPRs to VGPRs, this seldom limits scheduling
	- Don't take this as a challenge

ROCm blog about Register Pressure:

<https://rocm.blogs.amd.com/software-tools-optimization/register-pressure/README.html>

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Launching kernels has a cost

- "Cold" Launch Latency
	- If device is idle when kernel is launched, it takes a while for waves to be scheduled
	- Once waves start being scheduled, it can still take some time for the device to fill
- "Hot" Launch Latency
	- Launching kernel when device is busy can hide much of the startup cost
	- However, kernels in the same HIP stream are ordered. Therefore, all waves in a kernel in a HIP stream must complete before any wave from the next kernel in the stream can be scheduled.
		- Some cycles are spent at kernel boundaries for flushing writes from kernel
- Kernels that are too short (<< 1ms) suffer from kernel launch overhead

Fuse kernels to reduce launch latencies

• Also reduce data movement as shown here:

2 reads of "a" and "b", "c" written out and read back before being written out again!

Reduce or Avoid Synchronization

- Thread block synchronization
	- Synchronizes wavefronts in a thread block
	- Expensive in large work groups, don't over use it
- Host-side synchronization
	- Memory operations (hipMalloc, hipFree, etc.) implicitly synchronize activity on the device => unexpected low perf
	- Move memory allocations out of inner loops. This may cause a rethinking of the current algorithm
- Use asynchronous memory copies (H<->D) with pinned host buffers
	- avoid host-side synchronization
	- overlap copies with compute

A Note about Atomics

- If using atomic operations on MI200, compile with -munsafe-fp-atomics to use hardware atomics on FP data in GPU memory
	- Not needed on MI300
- Reducing contention in atomic operations can improve performance
- On MI300 GPUs, atomics are performed in the AMD Infinity Cache^{r m instead of the L2 cache}
	- Infinity Cache is a Memory Adjacent Last Level (MALL) cache
	- L2 is distributed and local to Accelerator Compute Dies (XCDs)

Minimize Thread Divergence

- Instructions in divergent paths are executed multiple times, some threads masked off each time
- Try minimizing divergent sections even if it means values computed by some threads will be discarded eventually

To compare assembly for both cases: <https://godbolt.org/z/4fEqvE8zP>

Warp shuffle/cross-lane functions

- Exchange data in registers between threads in wavefront
- Uses the same hardware fabric as LDS, but no storage in LDS
- Works on a common "width" where every thread is using the same width up to the wavefront size of 64

Summary

- Kernel performance may be limited by
	- memory bandwidth
	- lack of compute resources
	- latencies
- Performance optimization involves balancing many constraints
	- Reduce data movement and access data in a coalesced manner
	- Avoid unnecessary compute and excessive synchronization
	- Adjust occupancy while considering resource requirements
- Most importantly, have fun optimizing your kernels!

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